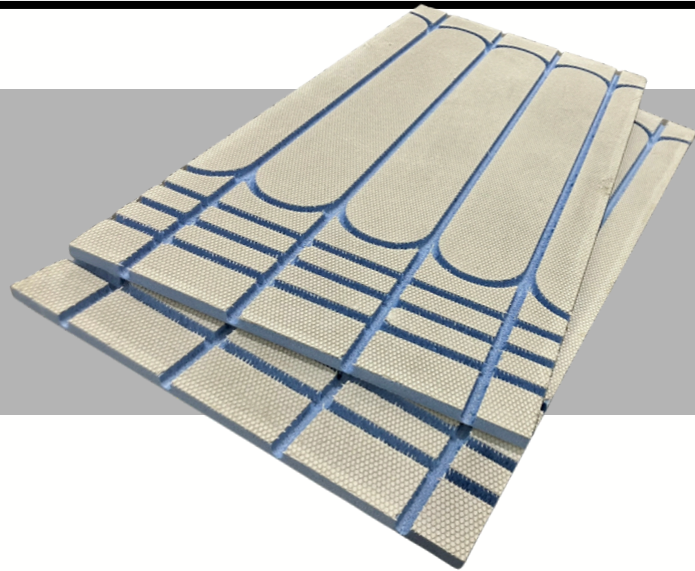




TEKGROUP



LITE LP UFH BOARD

A low-profile insulated under floor heating board.

A high compressive strength 300 kPa XPS underfloor heating insulation board for low profile systems.

It has durable cement coatings on either face that are suitable for the direct application of tiles or wood flooring (on underlay).

The board size is 1200mm x 600mm x 20mm, being grooved on one face as required to suit either 12 or 16mm diameter underfloor heating pipes, with radius returns as standard.

Other routed pipe layouts and patterns are available, further details upon request from the Sales Office.

TEKWARM

INSTALLATION

Tekwarm Lite LP UFH Boards make for a speedy installation over a flat level sub floor.

TIMBER BASE

For applications onto timber the panels should always be fixed with Tekwarm mechanical fixings and washers. Fixings should be of a suitable length for application.

CONCRETE BASE

Tekwarm boards laid directly onto concrete should be adhered with a bed of combed tile adhesive (S1 or equivalent). On occasions mechanical fixings will also be required dependant on substrate.

FINISHING

For most applications an additional board is not required and flooring can be laid directly to the upper surface.

- Wood flooring products should be applied using a suitable underlay as per manufacturer's instructions.
- Flooring grade tiles can be laid on a suitable combed tile adhesive layer.
- Other finishes will require a separating layer of Tekwarm Construction Board prior to their installation.

SUITABLE FOR

Tekwarm Lite LP UFH Board is suitable for new build or retro fit installations, and the standard pattern board is normally available from stock.

TEKGROUP

Unit 1 Power Park, Commercial Road,
Goldthorpe Industrial Estate,
Rotherham,
S63 9NBL

T: 01709 261 007
www.thetekgroup.co.uk